Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
			*** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-03-11
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to " Supplier Comment" section	Representative Email *	Refer to " Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

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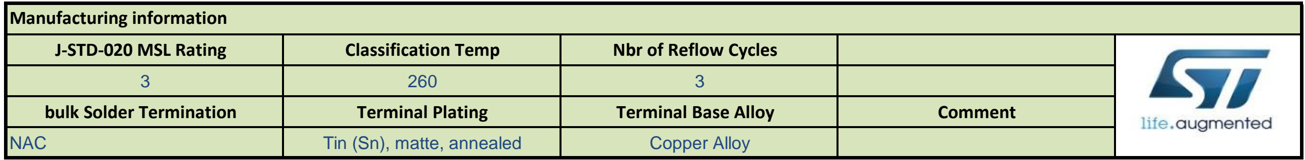
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9733XP	G6N3*UH33BBM	A	MU1A	2016-03-11
	Amount	UoM	Unit type	ST ECOPACK Grade
	1910.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	10.3x7.5x2.25	28	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	**true**
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	**Description**

QueryList : REACH-17th Dec 2015	
Query	**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	G6N3*UH33BBM					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	12.742	mg	supplier	die	Silicon (Si)	7440-21-3		12.191	mg	956757	6383
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.091	mg	7142	48
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.012	mg	942	6
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.020	mg	1570	10
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.246	mg	19306	129
Die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.007	mg	549	4
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.019	mg	1491	10
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.062	mg	4866	32
Die				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.094	mg	7377	49
Leadframe	Copper & its alloys	140.959	mg	supplier	alloy	Copper (Cu)	7440-50-8		135.505	mg	961308	70945
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		3.187	mg	22609	1669
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.192	mg	1362	101
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.167	mg	1185	87
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		1.908	mg	13536	999
Die attach		8.199	mg	JIG - R	Soft Solder	Lead (Pb)	7439-92-1	7a-Lead in high me	7.994	mg	974997	4185
Die attach				supplier	Soft Solder	Silver (Ag)	7440-22-4		0.123	mg	15002	64
Die attach				supplier	Soft Solder	Tin (Sn)	7440-31-5		0.082	mg	10001	43
Bonding wire		1.550		supplier	wire	Gold (Au)	7440-57-5		1.534	mg	989677	803
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		0.009	mg	5806	5
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.005	mg	3226	3
Bonding wire				supplier	wire	Platinium (Pt)	7440-06-4		0.002	mg	1290	1
encapsulation		1741.673	mg	supplier	mold compound	Phenol Resin	205830-20-2		69.667	mg	40000	36475
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		52.250	mg	30000	27356
encapsulation				supplier	mold compound	epoxy resin	na		52.250	mg	30000	27356
encapsulation				supplier	mold compound	carbon black	1333-86-4		3.483	mg	2000	1824
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		1564.023	mg	898000	818860
connections coating	Solder	4.877	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.877	mg	1000000	2553